



Product/Process Change Notice - PCN 14_0005 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

PCN Title: Assembly transfer to Amkor Philippines and Test Transfer to STATS ChipPAC China of Select LFCSP Products

Publication Date: 27-Jan-2014

Effectivity Date: 27-Apr-2014 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change

ADI is transferring to qualified subcontractor Amkor Philippines for assembly and to subcontractor STATS ChipPAC China for test of select LFCSP products.

The mold compound is changing from Sumitomo G770 to Sumitomo G700. The die attach epoxy, the package outline dimensions and the wire diameter of each product will be maintained. See BOM attachment for details.

Reason For Change

ADI is transferring due to the closure of STATS ChipPAC Malaysia at the end of 2014.

ADI's assembly subcontractors manufacture products using Analog Devices specified manufacturing flows, materials, process controls and monitors, ensuring the same level of quality and reliability on products they receive from the new site.

Impact of the change (positive or negative) on fit, form, function & reliability

The Transfer will have no impact on the form, fit, function and reliability of the devices.

Product Identification *(this section will describe how to identify the changed material)*

The parts that will be assembled after the transfer will be identified by assembly lot and the country of origin.

Summary of Supporting Information

Qualification has been performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Report Summary. Test correlation and validation will also be performed.

Supporting Documents

Attachment 1: Type: Qualification Report Summary

ADI_PCN_14_0005_Rev_-_Qualification Report Summary.pdf

Attachment 2: Type: Test Correlation Plan

Attachment 3: Type: Detailed Change Description

ADI_PCN_14_0005_Rev_-_BOM.xlsx

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative

Americas: PCN_Americas@analog.com

Europe: PCN_Europe@analog.com

Japan: PCN_Japan@analog.com

Rest of Asia: PCN_ROA@analog.com

Appendix A - Affected ADI Models**Added Parts On This Revision - Product Family / Model Number (22)**

AD5644 / AD5644ACPZ-1-RL7	AD5644 / AD5644BCPZ-RL7	AD5628 / AD5628ACPZ-1-RL7	AD5628 / AD5628ACPZ-2-RL7	AD5628 / AD5628BCPZ-2-RL7
AD5628 / AD5628BCPZ-2-U1	AD5629R / AD5629RACPZ-2-RL7	AD5629R / AD5629RACPZ-3-RL7	AD5629R / AD5629RBCPZ-1-RL7	AD5629R / AD5629RBCPZ-2-RL7
AD5668 / AD5668ACPZ-2-RL7	AD5668 / AD5668ACPZ-3-RL7	AD5668 / AD5668BCPZ-1-RL7	AD5668 / AD5668BCPZ-1500RL7	AD5668 / AD5668BCPZ-2-RL7
AD5668 / AD5668BCPZ-2500RL7	AD5669R / AD5669RACPZ-2-RL7	AD5669R / AD5669RACPZ-3-RL7	AD5669R / AD5669RBCPZ-1-RL7	AD5669R / AD5669RBCPZ-1500R7
AD5669R / AD5669RBCPZ-2-RL7	AD5669R / AD5669RBCPZ-2500R7			

Appendix B - Revision History

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	27-Jan-2014	27-Apr-2014	Initial Release

Analog Devices, Inc.

DocId:2719 Parent DocId:2663 Layout Rev:7